

COM-HPC Solder Mode

COM-HPC Carrier Board Standoff



Material	
Material	Stainless Steel
Surface Treatment	
Surface Treatment	Tin Plated

Headquarter

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Note : All product specifications are subject to change without notice

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EFCO Part Number	Thread Size	Head Length	Suggested PCB Hole Size	Board to Board Height
40100-A00014-B.0	M2.5	5mm	Ø3.2	5mm
40100-000047-B.0	M2.5	8mm	Ø3.2	10mm

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